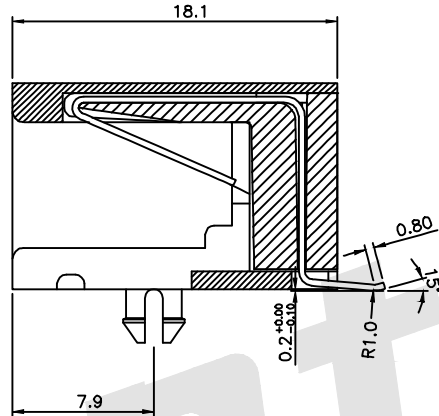
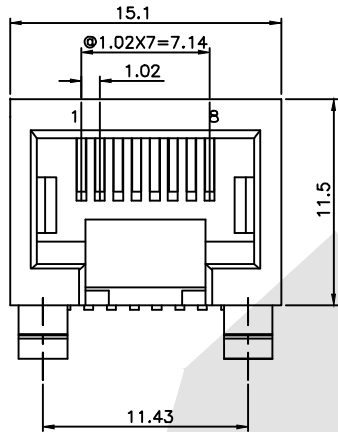
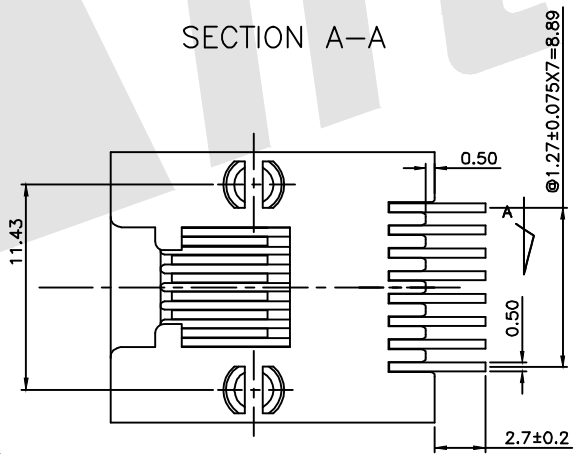
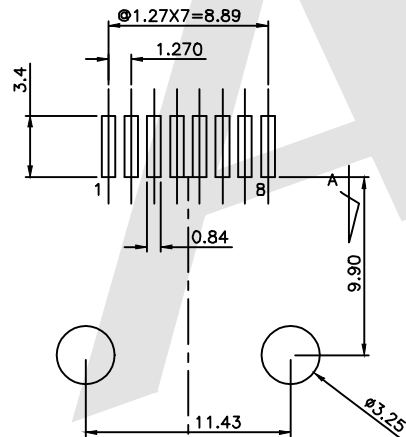


HSF



SECTION A-A



PC BOARD LAYOUT COMPONENT SIDE SHOWN

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.35mm
- 3. PLATING :SELECTING GOLD PLATING 1u~50u"OVER NICKEL IN CONTACT AREA. 150u" TIN OVER NICKEL IN SOLDER AREA.

- 4. SHIELD :0.25mm THICKNESS COPPER ALLY WITH NICKEL . PLATEL

ELECTRICAL:

- 1. VOLTAGE PATING :125 VAC RMS.
- 2. CURRENT PATING :1.5 AMP
- 3. CONTACT RESISTANCE :35 MILLIOHMS MAX
- 4. INSULATION RESISTANCE:1000 MEGOHMS MIN @ 500V DC.
- 5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60Hz. 1MIN

MECHANICAL:

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTION PRE-SOLDER :10LB MIN

ENVIRONMENTAL:

- 1. STORAGE : -40°C TO +85°C .
- 2. OPERATION : -40°C TO +85°C .
- 3. IR REFLOW SOLDERING

TEMPERATURE:255~265°C (5~10 SECONDS) MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5822 - 8P - 8C - X - A - X

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P,6P,4P)
- ③ NUMBER OF CONTACTS (8C,6C,4C)
- ④ Contact Plating
G0:Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin
- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
- ⑥ packing:
A: Tray packing
R: Tape & Reel

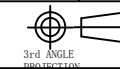
Unless Otherwise specified tolerance	
X. ±0.35	X.XX: ±0.20
X.X: ±0.25	X.XXX: ±0.15
SCALE: As Shown	UNIT: mm
DRAW Wu Sai	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

Antenk ANTENK ELECTRONICS CO.,LTD
[Http://www.antenk.com](http://www.antenk.com)
 E-mail:sales@antenk.com

TITLE:
RJ45 SIDE ENTRY SMT JACK 8P

DRAWING NO: ATRJ5822-8P8C-X-A-X

PRODUCT NO: ATRJ5822-8P8C-X-A-X



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REV	DESCRIPTION	DATE
1		
2		
3		
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